

FURUKAWA ELECTRONICS PRODUCTS

UV-TAPES For Semiconductor Processing

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NEW INNOVATIVE TAPE IMPROVES YIELD AND SAVES COST

UV-TAPE FOR WAFER BACKGRINDING & ETCHING

SP-Series

A new innovative adhesive tape for wafer backgrinding and etching. SP tape's excellent shock and vibration absorption protects the wafer against breakage and damage during backgrinding. It's strong resistance to acids protects the wafer during the etching process without application of photo resist. A flash of UV eliminates SP tape's high adhesion, permitting virtually no stress tape removal with no adhesive residue.

Excellent Cushion!

Applicable to 100 μ m Height Solder Bump!

No Washing-process!

Excellent Surface Protection!

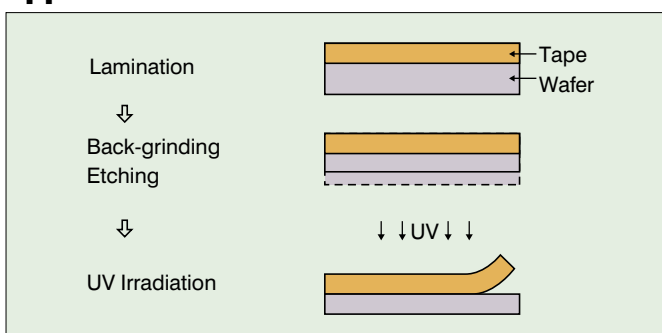
Superior Resistance to Acid Etchants!



Features

1. High adhesion prevents wafer breakage caused by delamination of tape due to lack of tackiness.
2. Hardness of backing film and adhesive is controlled to optimize shock and vibration absorption.
3. Strong resistance to acid etchants makes it possible to eliminate resist-process.
4. Characteristics of near zero adhesion after UV irradiation eliminate possibility of residues and wafer breakage.
5. Consisting of strictly selected raw materials, contains little impurities and provides virtually no contamination.

Applications



UV-TAPE FOR WAFER DICING

UC-Series

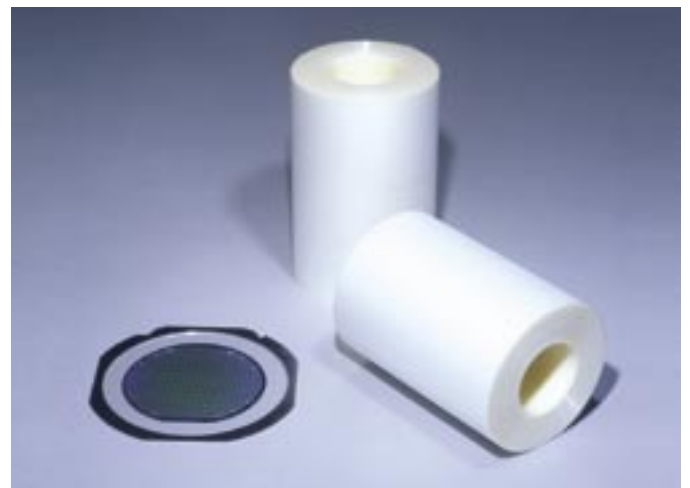
A new innovative adhesive tape for wafer dicing, that allows Full Cut Method.

The high adhesion of UC tape prevents chip flying and makes it possible to minimize chipping during dicing. Its adhesive becomes non-sticky when exposed to UV light. Even large chips, therefore can be easily picked up, virtually no stress and no adhesive residue.

No Chip Flying!

Stable Picking-up Chips!

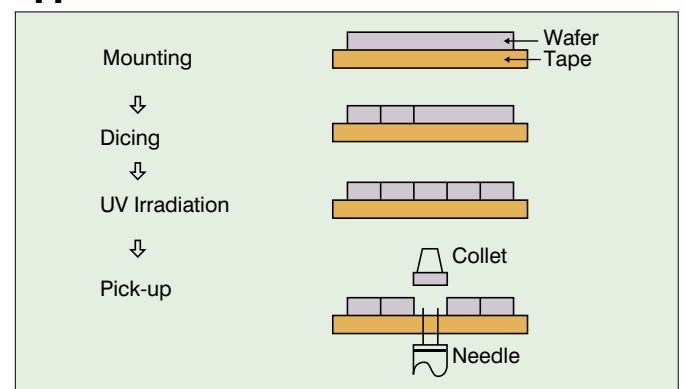
Applicable to Large Chips!



Features

1. High adhesion secures dies in place and avoids chip flying and chipping during dicing.
2. Characteristics of near zero adhesion after UV irradiation makes it possible to pick up dies free of stress.
3. Specially designed adhesive makes easy die-pick-up possible, regardless of kinds of wafer surface.
4. No contamination with harmful ionic substances or with migration of adhesive and its additives.

Applications



UV-TAPE FOR BGA/CSP PACKAGE DICING

FC-Series

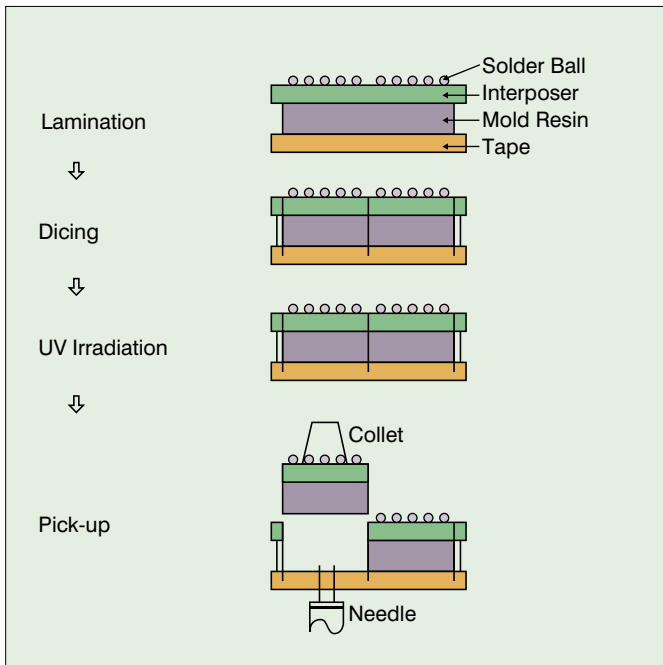
A new innovative adhesive tape for BGA/CSP package dicing.

No Package Flying!
Applicable to Low Illumination Lamp!

Features

1. High tuck strength avoids package flying during dicing.
2. Characteristics of near zero adhesion after UV irradiation makes it possible to pick up diced package easily.
3. No peeling of Ink Marking.
4. No adhesive residue in the laser marking area.

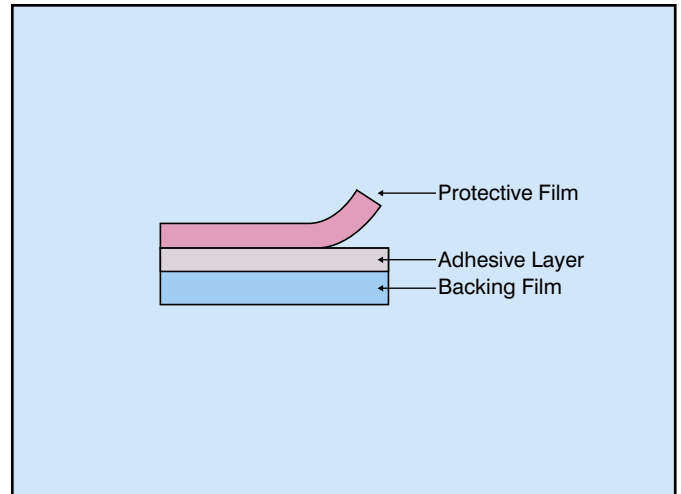
Applications



Adhesion Characteristics & Structure of UV-Tapes for Semiconductor Processing

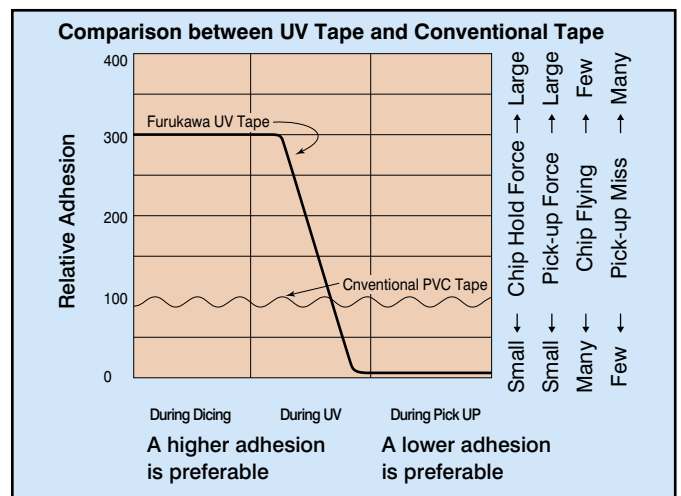
Structure

The composition of UV tapes is shown in the following illustration. Please peel off the protective film (separator) in usage.



Adhesion Characteristics

UV tapes can settle the wafers surely with the strong adhesive strength in the wafer dicing or grinding. And in picking-up or delamination process, tapes are easy to be peeled off from the wafer because the adhesive strength is very small after UV irradiation.



Acquirement of ISO 9001 certification



Furukawa Electric acquired the ISO 9001 certification for Global Quality Management System about the design, development and manufacture of tapes for semiconductor processing.

Acquirement of ISO 14001 certification



Furukawa Electric recognizes that preservation of the global environment is a critical issue for society, and shall incorporate consideration of environmental preservation issues into every phase of corporate activity, to contribute forwards the sustainable development of prosperous and bright society.

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